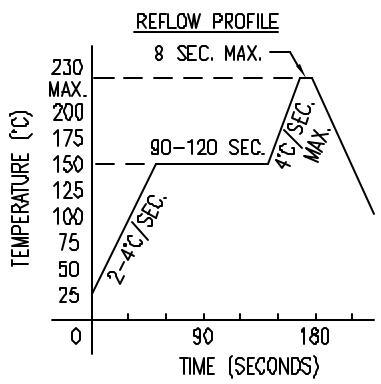
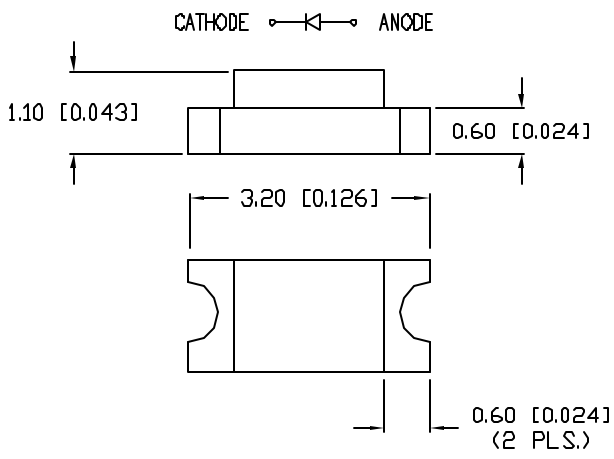
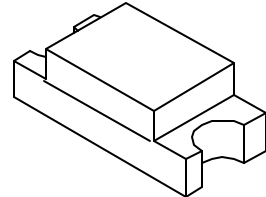
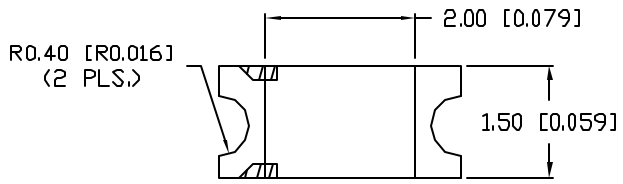


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REV.



ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $I_f=20\text{mA}$

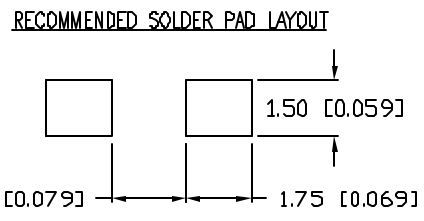
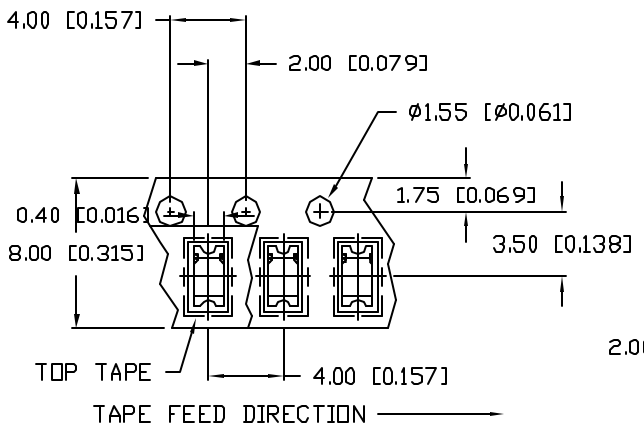
PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		940		nm	
SPECTRAL BANDWIDTH		45		nm	
FORWARD VOLTAGE		1.2	1.5	V_f	
REVERSE VOLTAGE	5.0			V_r	$I_f=10\mu\text{A}$
RADIANT INTENSITY		0.8		mW/SR	$I_f=20\text{mA}$
HALF ANGLE		± 80		degrees	

EPOXY LENS FINISH: WATER CLEAR

LIMITS OF SAFE OPERATION AT 25°C PER DIE

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	1	A
STEADY CURRENT	65	mA
POWER DISSIPATION	130	mW
DERATE FROM 25°C	-1.2	mW/ $^\circ\text{C}$
OPERATING, STORAGE TEMP.	-40 TO +85	$^\circ\text{C}$

* $t < 100\mu\text{s}$, DUTY $\leq 1\%$



NOTES:

- 2,000 PIECES PER REEL.
- THE CATHODE IS ORIENTED TOWARDS THE TAPE SPROCKET HOLE

CAUTION: MOISTURE SENSITIVE DEVICE

- SHELF LIFE IN SEALED BAG:
12 MONTHS AT $<40^\circ\text{C}$ AND $<90\%$ RELATIVE HUMIDITY (RH).
- AFTER THIS BAG IS OPENED, DEVICES HAVE TO BE MOUNTED WITHIN 48 HOURS OR STORED AT $<30\%$ RH.

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*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X= ± 1 (± 0.039), XX= ± 0.5 (± 0.020), XXX= ± 0.25 (± 0.010), XXXX= ± 0.127 (± 0.005). LEAD SIZE= ± 0.05 (0.002), LEAD LENGTH= ± 0.75 (± 0.030), MIN= +DECIMAL PRECISION -0.00, MAX.= +0.00 -DECIMAL PRECISION

REV.	PART NUMBER OED-EL1206C160-TR
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3.2 x 1.5mm P.C.B. 940nm IR EMITTING DIODE,
1206 SMD PACKAGE, WATER CLEAR LENS.

RELIABILITY NOTE
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY: CT	CHECKED BY:	APPROVED BY:	DATE: 2.3.03
			PAGE: 1 OF 1
			SCALE: N/A